

# Molding Type Module IGBT, Chopper in 1 Package, 1200 V and 200 A



PRODUCT SUMMARY					
$V_{CES}$	1200 V				
$I_C$ at $T_C = 80$ °C	200 A				
$V_{CE(on)}$ (typical) at $I_C = 200 \text{ A}, 25 ^{\circ}\text{C}$	1.8 V				
Speed	8 kHz to 30 kHz				
Package	Double INT-A-PAK				
Circuit	Chopper high side switch				

#### **FEATURES**





- 10 µs short circuit capability
- V<sub>CE(on)</sub> with positive temperature coefficient
- Maximum junction temperature 150 °C
- · Low inductance case
- · Fast and soft reverse recovery antiparallel FWD
- Isolated copper baseplate using DCB (Direct Copper Bonding) technology
- Material categorization: for definitions of compliance please see <a href="https://www.vishav.com/doc?99912">www.vishav.com/doc?99912</a>

#### TYPICAL APPLICATIONS

- · AC inverter drives
- Switching mode power supplies
- Electronic welders

#### **DESCRIPTION**

Vishay's IGBT power module provides ultra low conduction loss as well as short circuit ruggedness. It is designed for applications such as general inverters and UPS.

ABSOLUTE MAXIMUM RATINGS (T <sub>C</sub> = 25 °C unless otherwise noted)				
PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS
Collector to emitter voltage	V <sub>CES</sub>		1200	V
Gate to emitter voltage	V <sub>GES</sub>		± 20	V
Collector current		T <sub>C</sub> = 25 °C	420	
Collector current	I <sub>C</sub>	T <sub>C</sub> = 80 °C	200	
Pulsed collector current	I <sub>CM</sub> <sup>(1)</sup>	t <sub>p</sub> = 1 ms	400	А
Diode continuous forward current	I <sub>F</sub>	T <sub>C</sub> = 80 °C	200	
Diode maximum forward current	I <sub>FM</sub>	t <sub>p</sub> = 1 ms	400	
Maximum power dissipation	P <sub>D</sub>	T <sub>J</sub> = 150 °C	1562	W
Short circuit withstand time	t <sub>SC</sub>	T <sub>J</sub> = 125 °C	10	μs
RMS isolation voltage	V <sub>ISOL</sub>	f = 50 Hz, t = 1 min	2500	V
l <sup>2</sup> t-value, diode	l <sup>2</sup> t	V <sub>R</sub> = 0 V, t = 10 ms, T <sub>J</sub> = 125 °C	6900	A <sup>2</sup> s

#### Note

<sup>(1)</sup> Repetitive rating: pulse width limited by maximum junction temperature.



IGBT ELECTRICAL SPECIFICATIONS (T <sub>C</sub> = 25 °C unless otherwise noted)							
PARAMETER	SYMBOL TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS	
Collector to emitter breakdown voltage	V <sub>(BR)CES</sub>	T <sub>J</sub> = 25 °C	1200	-	-		
Collector to emitter voltage	V	$V_{GE} = 15 \text{ V}, I_{C} = 200 \text{ A}, T_{J} = 25 \text{ °C}$	-	1.8	-	v	
Collector to entitler voltage	$V_{CE(on)}$	V CE(on)	$V_{GE} = 15 \text{ V}, I_{C} = 200 \text{ A}, T_{J} = 125 \text{ °C}$	-	2.0	-	]
Gate to emitter threshold voltage	V <sub>GE(th)</sub>	$V_{CE} = V_{GE}$ , $I_{C} = 4$ mA, $T_{J} = 25$ °C	5.0	6.2	7.0		
Collector cut-off current	I <sub>CES</sub>	$V_{CE} = V_{CES}$ , $V_{GE} = 0$ V, $T_{J} = 25$ °C	-	-	5.0	mA	
Gate to emitter leakage current	I <sub>GES</sub>	$V_{GE} = V_{GES}$ , $V_{CE} = 0$ V, $T_{J} = 25$ °C	-	-	400	nA	

SWITCHING CHARACTERISTICS	•					
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Turn-on delay time	t <sub>d(on)</sub>		-	110	-	ns mJ
Rise time	t <sub>r</sub>		-	60	-	
Turn-off delay time	t <sub>d(off)</sub>	$V_{CC} = 600 \text{ V}, I_{C} = 200 \text{ A}, R_{g} = 5 \Omega,$	-	360	-	
Fall time	t <sub>f</sub>	V <sub>GE</sub> = ± 15 V, T <sub>J</sub> = 25 °C	-	60	-	
Turn-on switching loss	E <sub>on</sub>		-	18	-	
Turn-off switching loss	E <sub>off</sub>		-	15	-	
Turn-on delay time	t <sub>d(on)</sub>		-	120	-	- ns
Rise time	t <sub>r</sub>		-	60	-	
Turn-off delay time	t <sub>d(off)</sub>	$V_{CC} = 600 \text{ V}, I_{C} = 200 \text{ A}, R_{q} = 5 \Omega,$	-	420	-	
Fall time	t <sub>f</sub>	V <sub>GE</sub> = ± 15 V, T <sub>J</sub> = 125 °C	_	70	-	
Turn-on switching loss	E <sub>on</sub>		_	21	-	
Turn-off switching loss	E <sub>off</sub>	1	-	18	-	- mJ
Input capacitance	C <sub>ies</sub>		-	18.0	-	
Output capacitance	C <sub>oes</sub>	V <sub>GE</sub> = 0 V, V <sub>CE</sub> = 25 V, f = 1.0 MHz	-	1.64	-	nF
Reverse transfer capacitance	C <sub>res</sub>	1	-	0.72	-	
SC data	I <sub>SC</sub>	$t_{SC} \leq 10 \; \mu s,  V_{GE} = 15 \; V,  T_J = 125 \; ^{\circ}C, \\ V_{CC} = 900 \; V,  V_{CEM} \leq 1200 \; V$	-	1080	-	А
Internal gate resistance	R <sub>gint</sub>		-	2	-	Ω
Stray inductance	L <sub>CE</sub>		-	-	20	nH
Module lead resistance, terminal to chip	R <sub>CC'+EE'</sub>	T <sub>C</sub> = 25 °C	-	0.35	-	mΩ

<b>DIODE ELECTRICAL SPECIFICATIONS</b> (T <sub>C</sub> = 25 °C unless otherwise noted)								
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS	
Diode forward voltage	V <sub>F</sub> I <sub>F</sub> = 200 A	I 200 A	T <sub>J</sub> = 25 °C	ı	2.0	ı	V	
blode forward voltage		T <sub>J</sub> = 125 °C	ı	2.2	ı	]		
Diode reverse recovery charge	Q <sub>rr</sub>	Q <sub>rr</sub>	T <sub>J</sub> = 25 °C	-	24	-		
Diode reverse recovery charge			T <sub>J</sub> = 125 °C	-	32	-	μC	
Diada mada waxaya waxayam ayawant	I <sub>rr</sub>		$I_F = 200 \text{ A}, V_R = 600 \text{ V},$	T <sub>J</sub> = 25 °C	-	240	-	Α
Diode peak reverse recovery current		$I_{rr}$	T <sub>J</sub> = 125 °C	-	280	-		
Diada rayayaa raaayany anaray	_	GL -	T <sub>J</sub> = 25 °C	-	6	-	ml	
Diode reverse recovery energy	⊏rec	E <sub>rec</sub>	T <sub>J</sub> = 125 °C	-	10	-	mJ	



THERMAL AND MECHANICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Operating junction temperature range	TJ		-40	-	150	°C
Storage temperature range	T <sub>STG</sub>		-40	-	125	
Junction to case IGBT (per 1/2 module			-	-	0.08	
Diode (per 1/2 module)	R <sub>thJC</sub>		-	-	0.17	K/W
Case to sink	R <sub>thCS</sub>	Conductive grease applied	-	0.035	-	
Mounting touring		Power terminal screw: M6	2.5 to 5.0		Nm	
Mounting torque		Mounting screw: M6	3.0 to 6.0		INIII	
Weight				300		g

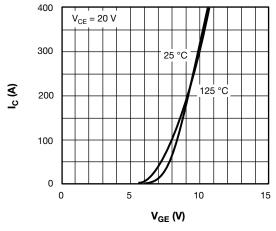


Fig. 1 - Typical Output Characteristics

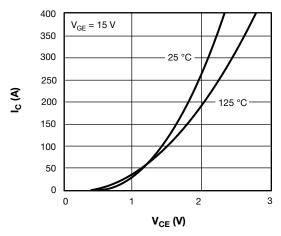


Fig. 2 - Typical Transfer Characteristics

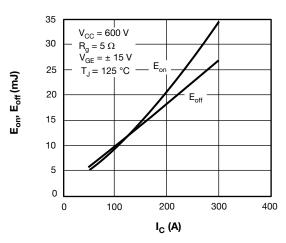


Fig. 3 - Switching Loss vs. I<sub>C</sub>

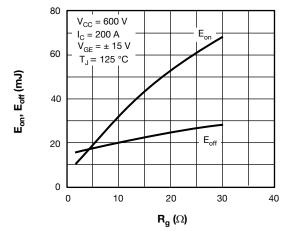


Fig. 4 - Switching Loss vs. R<sub>g</sub>

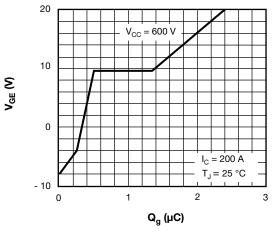


Fig. 5 - Gate Charge Characteristics

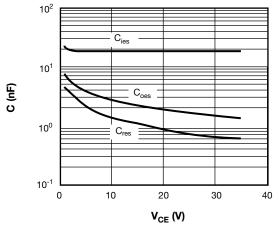


Fig. 6 - Typical Capacitance vs. Collector to Emitter Voltage

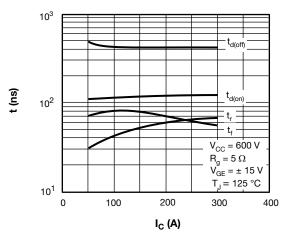


Fig. 7 - Typical Switching Time vs. I<sub>C</sub>

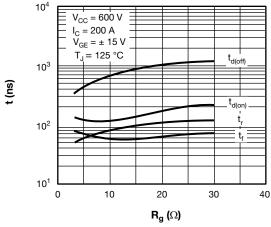


Fig. 8 - Typical Switching Times vs. Gate Resistance Rq

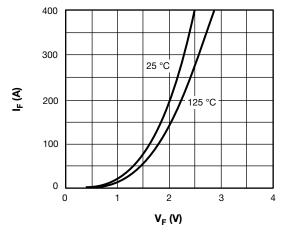


Fig. 9 - Diode Typical Forward Characteristics

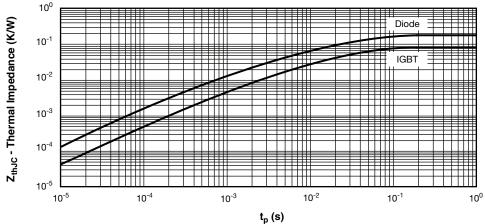
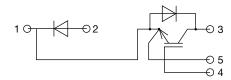


Fig. 10 - Transient Thermal Impedance

### **CIRCUIT CONFIGURATION**

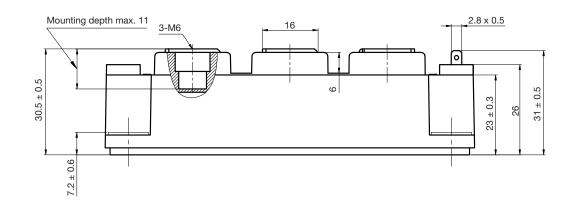


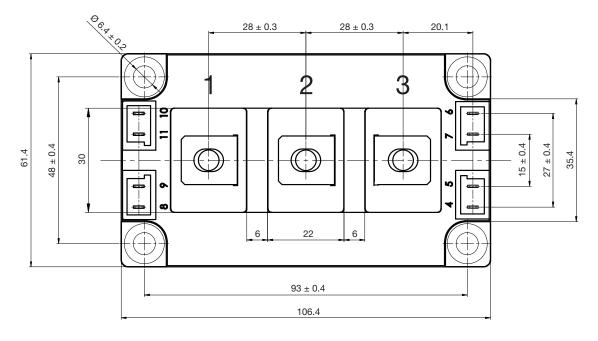
LINKS TO RELATED DOCUMENTS			
Dimensions	www.vishay.com/doc?95525		



## **Double INT-A-PAK**

### **DIMENSIONS** in millimeters (inches)







## **Legal Disclaimer Notice**

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